



Click [here](#) for the 3D model.

### Dimensions

Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.07mm
S	0.7mm MIN
B	0.35mm +/-0.15mm

### Packaging Specifications

Packaging	Waffle, Tray
Packaging Quantity	368

### General Information

Series	SMD Indust COG HT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Gold
Marking	No
AEC-Q200	No
Component Weight	3.7 mg
Miscellaneous	Moisture Sensitive Packaging. Gold (Au) 1.97 - 11.8 micro inches.
Shelf Life	26 Weeks
MSL	1

### Specifications

Capacitance	1000 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	1%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms